

AMENDMENTS TO THE CLAIMS:

This listing of claims will replace all prior versions, and listings of claims in the application:

LISTING OF CLAIMS:

1. (original) A jig for calcining an electronic component comprising a substrate and a zirconia surface layer formed on the substrate and having an arithmetic average roughness "Ra" from 5 to 40 μ m, or a ten-point average roughness "Rz" from 30 to 130 μ m, or a maximum height "Ry" from 40 to 200 μ m characterized in that a skewness (deflection) "Rsk" of the zirconia surface layer is from -0.5 to 0.5.

2. (original) A jig for calcining an electronic component comprising a substrate, an intermediate layer formed on the substrate and a zirconia surface layer formed on the intermediate layer and having an arithmetic average roughness "Ra" from 5 to 40 μ m, or a ten-point average roughness "Rz" from 30 to 130 μ m, or a maximum height "Ry" from 40 to 200 μ m, characterized in that a skewness (deflection) "Rsk" of the zirconia surface layer is from -0.5 to 0.5.

3. (currently amended) The jig for calcining the electronic component as claimed in claim 1 [[or 2]], wherein the zirconia surface layer includes from 50 to 75 % in weight of coarse

particle aggregate having from 80 to 300 mesh and 50 to 25 % in weight of fine particle bond phase having an average particle size from 0.1 to 10 μ m.

4. (original) A jig for calcining an electronic component comprising a substrate and a zirconia surface layer formed on the substrate and having an arithmetic average roughness "Ra" from 5 to 40 μ m, or a ten-point average roughness "Rz" from 30 to 130 μ m, or a maximum height "Ry" from 40 to 200 μ m, characterized in that an acutance (kurtosis) "Rku" of the zirconia surface layer is from 2 to 3.

5. (original) A jig for calcining an electronic component comprising a substrate, an intermediate layer formed on the substrate and a zirconia surface layer formed on the intermediate layer and having an arithmetic average roughness "Ra" from 5 to 40 μ m, or a ten-point average roughness "Rz" from 30 to 130 μ m, or a maximum height "Ry" from 40 to 200 μ m, characterized in that an acutance (kurtosis) "Rku" of the zirconia surface layer is from 2 to 3.

6. (currently amended) The jig for calcining the electronic component as claimed in claim 4 [[or 5]], wherein the zirconia surface layer includes from 50 to 75 % in weight of coarse particle aggregate having from 80 to 300 mesh and 50 to 25 % in

weight of fine particle bond phase having an average particle size from 0.1 to 10 μ m.

7. (original) A jig for calcining an electronic component comprising a substrate and a zirconia surface layer formed on the substrate, characterized in that a central surface average roughness "Sa" of the zirconia surface layer is from 10 to 40 μ m.

8. (original) A jig for calcining an electronic component comprising a substrate, an intermediate layer formed on the substrate and a zirconia surface layer formed on the intermediate layer, characterized in that a central surface average roughness "Sa" of the zirconia surface layer is from 10 to 40 μ m.

9. (currently amended) The jig for calcining the electronic component as claimed in claim 7 [[or 8]], wherein the zirconia surface layer includes from 50 to 75 % in weight of coarse particle aggregate having from 80 to 300 mesh and 50 to 25 % in weight of fine particle bond phase having an average particle size from 0.1 to 10 μ m.

10. (original) A jig for calcining an electronic component comprising a substrate and a zirconia surface layer formed on the substrate, characterized in that a wear resistance in a

reciprocating wear test conducted in accordance with JIS-H8503 is from 10 to 200 (DS/mg).

11. (original) A jig for calcining an electronic component comprising a substrate, an intermediate layer formed on the substrate and a zirconia surface layer formed on the intermediate layer, characterized in that a wear resistance in a reciprocating wear test conducted in accordance with JIS-H8503 is from 10 to 200 (DS/mg).

12. (currently amended) The jig for calcining the electronic component as claimed in claim 10 [[or 11]], wherein the zirconia surface layer includes from 50 to 75 % in weight of coarse particle aggregate having from 80 to 300 mesh and 50 to 25 % in weight of fine particle bond phase having an average particle size from 0.1 to 10 μ m bonded with each other by a sintering aid made of two or more metal oxides for increasing the wear resistance.

13. (original) A jig for calcining an electronic component comprising a substrate and a zirconia surface layer formed on the substrate, characterized in that a thermal shock resistance ΔT ($=T_1-T_2$) is 400°C or more expressed as a temperature difference of rapid cooling which generates strength reduction in a rapid

cooling bending test where the jog for calcining the electronic component is rapidly cooled from specified temperature T1 to T2.

14. (original) A jig for calcining an electronic component comprising a substrate, an intermediate layer formed on the substrate and a zirconia layer formed on the intermediate layer, characterized in that a thermal shock resistance ΔT is 400°C or more.

15. (original) The jig for calcining the electronic component as claimed in claim 13, wherein a thickness of the zirconia layer formed on the substrate is 500 μm or less, and a relative density of the zirconia surface layer is between 40 % and 80% both inclusive.

16. (original) The jig for calcining the electronic component as claimed in claim 14, wherein a total thickness of the zirconia layer formed on the alumina intermediate layer (alumina intermediate layer + zirconia layer) is 500 μm or less; a relative density of the zirconia layer is between 40 % and 80% both inclusive; and a relative density of the alumina intermediate layer is between 60 % and 90% both inclusive.

17. (currently amended) The jig for calcining the electronic component as claimed in claim 13 [[or 14]], wherein metal oxides

used as a sintering aid for calcining the zirconia layer coated on the substrate surface, alumina intermediate layer coated on the substrate surface, and the zirconia layer coated on the alumina intermediate layer.

18. (new) The jig for calcining the electronic component as claimed in claim 2, wherein the zirconia surface layer includes from 50 to 75 % in weight of coarse particle aggregate having from 80 to 300 mesh and 50 to 25 % in weight of fine particle bond phase having an average particle size from 0.1 to 10 μ m.

19. (new) The jig for calcining the electronic component as claimed in claim 5, wherein the zirconia surface layer includes from 50 to 75 % in weight of coarse particle aggregate having from 80 to 300 mesh and 50 to 25 % in weight of fine particle bond phase having an average particle size from 0.1 to 10 μ m.

20. (new) The jig for calcining the electronic component as claimed in claim 8, wherein the zirconia surface layer includes from 50 to 75 % in weight of coarse particle aggregate having from 80 to 300 mesh and 50 to 25 % in weight of fine particle bond phase having an average particle size from 0.1 to 10 μ m.

21. (new) The jig for calcining the electronic component as claimed in claim 11, wherein the zirconia surface layer includes

from 50 to 75 % in weight of coarse particle aggregate having from 80 to 300 mesh and 50 to 25 % in weight of fine particle bond phase having an average particle size from 0.1 to 10 μ m bonded with each other by a sintering aid made of two or more metal oxides for increasing the wear resistance.

22. (new) The jig for calcining the electronic component as claimed in claim 14, wherein metal oxides are used as a sintering aid for calcining the zirconia layer coated on the substrate surface, alumina intermediate layer coated on the substrate surface, and the zirconia layer coated on the alumina intermediate layer.